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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Suh Fei LIM	07/30/2007
Kok Wai CHEW	07/30/2007
Sanford Shao-Fu CHU	07/30/2007
Michael Chye Huat CHENG	07/30/2007

RECEIVING PARTY DATA

Name:	Chartered Semiconductor Manufacturing, Ltd.
Street Address:	60 Woodlands Industrial Park D Street 2
City:	Singapore
State/Country:	SINGAPORE
Postal Code:	738406

PROPERTY NUMBERS Total: 1

Property Type	Number	
Application Number:	11832642	

CORRESPONDENCE DATA

Fax Number: (656)846-2005

Correspondence will be sent via US Mail when the fax attempt is unsuccessful.

Phone: 65 9836 9908

Email: dexter.chin@horizonip.com.sg

Correspondent Name: Dexter CHIN
Address Line 1: 8 Kallang Sector
Address Line 2: East Wing 7th Floor

Address Line 4: Singapore, SINGAPORE 349282

ATTORNEY DOCKET NUMBER:	CSM P 2007 NAT 57 US 0
NAME OF SUBMITTER:	Dexter CHIN

Total Attachments: 5

PATENT REEL: 019634 FRAME: 0104

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PATENT REEL: 019634 FRAME: 0105 ASSIGNMENT

For good and valuable consideration, we, Suh Fei LIM, residing at Blk 511,

Woodlands Drive 14, #10-75, Singapore 730511, a citizen of Malaysia; Kok Wai CHEW,

residing at Blk 14B Lor 7 Toa Payoh #20-243, Singapore 312014, a citizen of Singapore;

Sanford Shao-Fu CHU, residing at 32 Nassim Hill, #09-34 Nassim Mansion, Singapore

258472, a citizen of United States of America; Michael Chye Huat CHENG, residing at 9

Greenleaf Lane, Singapore 279468, a citizen of Singapore;

Hereby sell, assign, and transfer to Chartered Semiconductor Manufacturing,

Ltd., a corporation of Singapore, having its principal place of business at 60 Woodlands

Industrial Park D Street 2, Singapore 738406,

hereinafter "Assignee", its successors, assigns and legal representatives, the entire

right, title and interest in and for the United States and all foreign countries, in and to any and

all improvements which are disclosed in the application for United States Letters Patent,

which has been executed by the undersigned concurrently here within, and is entitled:

INTEGRATED CIRCUIT SHIELD STRUCTURE AND METHOD OF

FABRICATION THEREOF

and in and to said application and all divisional, continuing substitute, renewal, reissue, and

all other applications for Letters Patent which have been or shall be filed in the United States

and all foreign countries on any of said improvements; and in and to all original and reissued

patents which have been or shall be filed in the United States and all foreign countries on said

improvements;

Agree that Assignee may apply for and receive Letters Patent for said improvements

in its own name, and that, when requested, without charge to but at the expense of said

Assignee, their successors, assigns, and legal representatives to carry out in good faith the

intent and purpose of this agreement, the undersigned will execute all divisional, continuing

substitute, renewal, reissue, and all other patent applications on any and all said

PATENT

REEL: 019634 FRAME: 0106

improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns, or representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

Date:

20/7/07

Suh Fei LIM

Witness 1:

tandoto Linewih

Witness 2:

Umashankar Mahalingam (Print name)

30/7/07 Date: (Signature)

Kok Wai CHEW

Witness 1:

(Signature)

Handoko Linewih

Witness 2:

Ministrative

(Signature)

UMashankar Mahalingam

(Print name)

Date:	30/7/67	Shoolhu
_	,	(Signature)
		Sanford Shao-Fu <u>CHU</u>
Witness 1:	(Signature) Handoko Linewih (Print name)	
Witness 2:	(Signature)	
	Umashankar Mahalingan (Print name)	

Date: 30/H07

(Signature)

Michael Chye Huat CHENG

Witness 1:

(Signature)

Handoko Linewih
(Print name)

Witness 2:

M. Comanuka

(Signature)

Umashantar Mahalingan

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